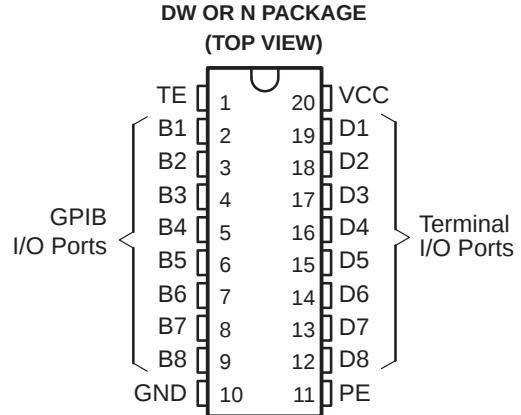


- Meets IEEE Standard 488-1978 (GPIB)
- 8-Channel Bidirectional Transceiver
- Power-Up/Power-Down Protection (Glitch Free)
- High-Speed, Low-Power Schottky Circuitry
- Low Power Dissipation . . . 72 mW Max Per Channel
- Fast Propagation Times . . . 22 ns Max
- High-Impedance pnp Inputs
- Receiver Hysteresis . . . 650 mV Typ
- Open-Collector Driver Output Option
- No Loading of Bus When Device Is Powered Down ($V_{CC} = 0$)



description

The SN75160B 8-channel general-purpose interface bus (GPIB) transceiver is a monolithic, high-speed, low-power Schottky device designed for two-way data communications over single-ended transmission lines. It is designed to meet the requirements of IEEE Standard 488-1978. The transceiver features driver outputs that can be operated in either the passive-pullup or 3-state mode. If talk enable (TE) is high, these ports have the characteristics of passive-pullup outputs when pullup enable (PE) is low and of 3-state outputs when PE is high. Taking TE low places these ports in the high-impedance state. The driver outputs are designed to handle loads up to 48 mA of sink current.

Output glitches during power up and power down are eliminated by an internal circuit that disables both the bus and receiver outputs. The outputs do not load the bus when $V_{CC} = 0$. When combined with the SN75161B or SN75162B management bus transceivers, the pair provides the complete 16-wire interface for the IEEE-488 bus.

The SN75160B is characterized for operation from 0°C to 70°C.

Function Tables

EACH DRIVER			
INPUTS			OUTPUT B
D	TE	PE	
H	H	H	H
L	H	X	L
H	X	L	$Z^\dagger$
X	L	X	$Z^\dagger$

EACH RECEIVER			
INPUTS			OUTPUT D
B	TE	PE	
L	L	X	L
H	L	X	H
X	H	X	Z

H = high level, L = low level, X = irrelevant, Z = high impedance

† This is the high-impedance state of a normal 3-state output modified by the internal resistors to V_{CC} and GND.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

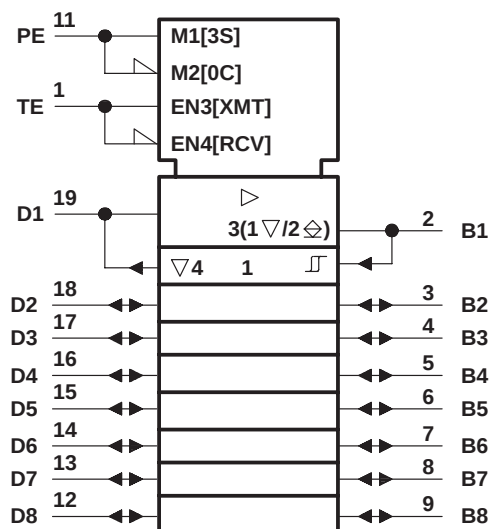
 **TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 1995, Texas Instruments Incorporated

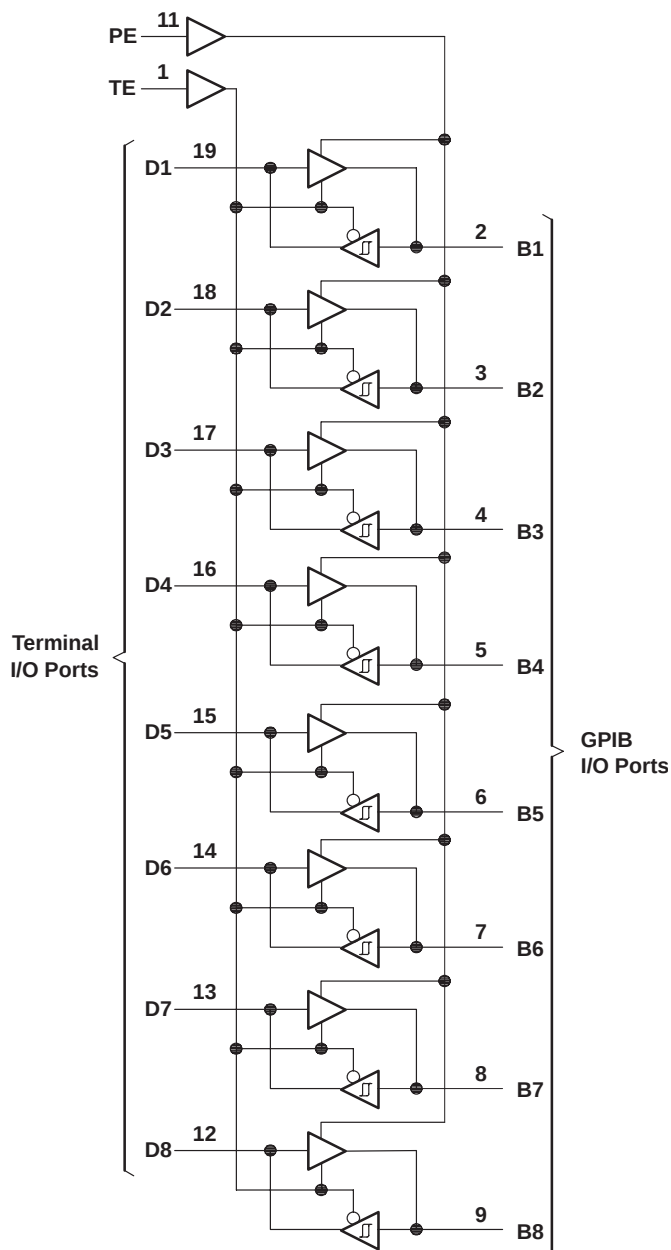
SN75160B
OCTAL GENERAL-PURPOSE
INTERFACE BUS TRANSCEIVER
 SLLS004B – OCTOBER 1985 – REVISED MAY 1995

logic symbol†

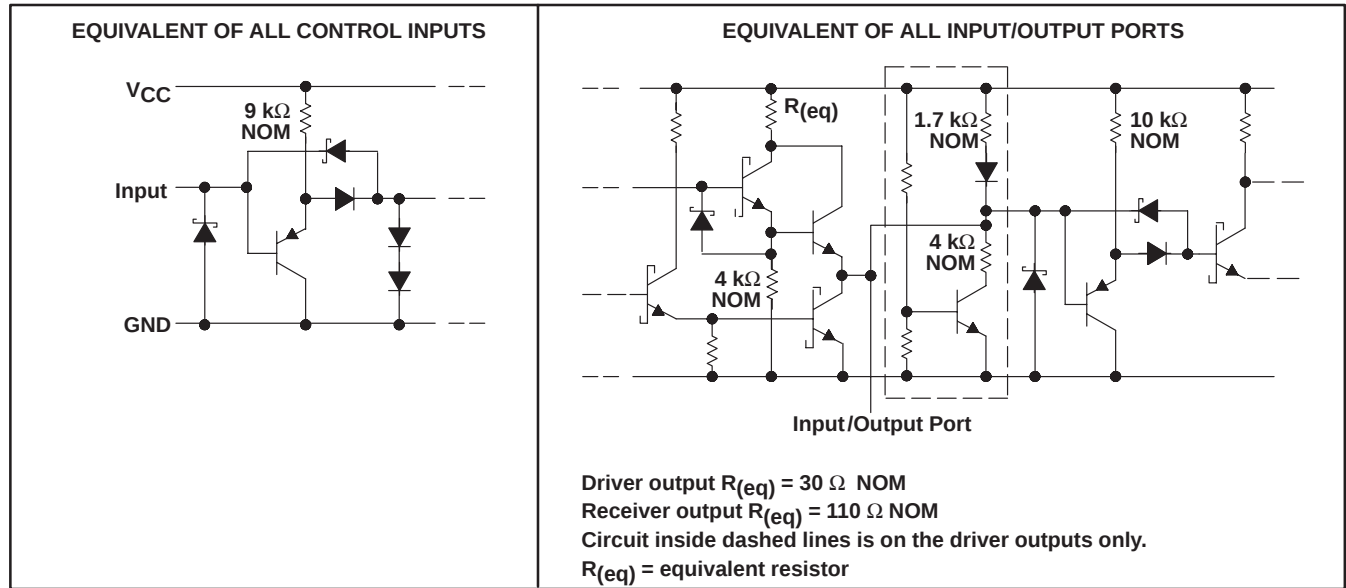


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
 ▽ Designates 3-state outputs
 ◇ Designates passive-pullup outputs

logic diagram (positive logic)



schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage, V_I	5.5 V
Low-level driver output current, I_{OL}	100 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A	0°C to 70°C
Storage temperature range, T_{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING
DW	1125 mW	9.0 mW/°C	720 mW
N	1150 mW	9.2 mW/°C	736 mW

SN75160B
OCTAL GENERAL-PURPOSE
INTERFACE BUS TRANSCEIVER
 SLLS004B – OCTOBER 1985 – REVISED MAY 1995

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.75	5	5.25	V
High-level input voltage, V_{IH}		2			V
Low-level input voltage, V_{IL}				0.8	V
High-level output current, I_{OH}	Bus ports with pullups active			–5.2	mA
	Terminal ports			–800	μ A
Low-level output current, I_{OL}	Bus ports			48	mA
	Terminal ports			16	
Operating free-air temperature, T_A		0		70	$^{\circ}$ C

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER			TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V_{IK}	Input clamp voltage		$I_I = -18$ mA			–0.8	–1.5	V
V_{hys}	Hysteresis voltage ($V_{IT+} - V_{IT-}$)	Bus	See Figure 8		0.4	0.65		V
V_{OH}	High-level output voltage	Terminal	$I_{OH} = -800$ μ A, TE at 0.8 V		2.7	3.5		V
		Bus	$I_{OH} = -5.2$ mA, PE and TE at 2 V		2.5	3.3		
V_{OL}	Low-level output voltage	Terminal	$I_{OL} = 16$ mA, TE at 0.8 V			0.3	0.5	V
		Bus	$I_{OL} = 48$ mA, TE at 2 V			0.35	0.5	
I_I	Input current at maximum input voltage	Terminal	$V_I = 5.5$ V			0.2	100	μ A
I_{IH}	High-level input current	Terminal	$V_I = 2.7$ V			0.1	20	μ A
I_{IL}	Low-level input current	Terminal	$V_I = 0.5$ V			–10	–100	μ A
$V_{I/O}(\text{bus})$	Voltage at bus port	Driver disabled	$I_{I(\text{bus})} = 0$		2.5	3.0	3.7	V
			$I_{I(\text{bus})} = -12$ mA				–1.5	
$I_{I/O}(\text{bus})$	Current into bus port	Power on	Driver disabled	$V_{I(\text{bus})} = -1.5$ V to 0.4 V	–1.3			mA
				$V_{I(\text{bus})} = 0.4$ V to 2.5 V	0		–3.2	
				$V_{I(\text{bus})} = 2.5$ V to 3.7 V			2.5	
				$V_{I(\text{bus})} = 3.7$ V to 5 V	0		2.5	
				$V_{I(\text{bus})} = 5$ V to 5.5 V	0.7		2.5	
				$V_{I(\text{bus})} = 5$ V to 5.5 V	0.7		2.5	
		Power off	$V_{CC} = 0$, $V_{I(\text{bus})} = 0$ to 2.5 V				–40	
I_{OS}	Short-circuit output current	Terminal			–15	–35	–75	mA
		Bus			–25	–50	–125	
I_{CC}	Supply current	No load	Receivers low and enabled			70	90	mA
			Drivers low and enabled			85	110	
$C_{I/O}(\text{bus})$	Bus-port capacitance	$V_{CC} = 0$ to 5 V, $f = 1$ MHz		$V_{I/O} = 0$ to 2 V,		16		pF

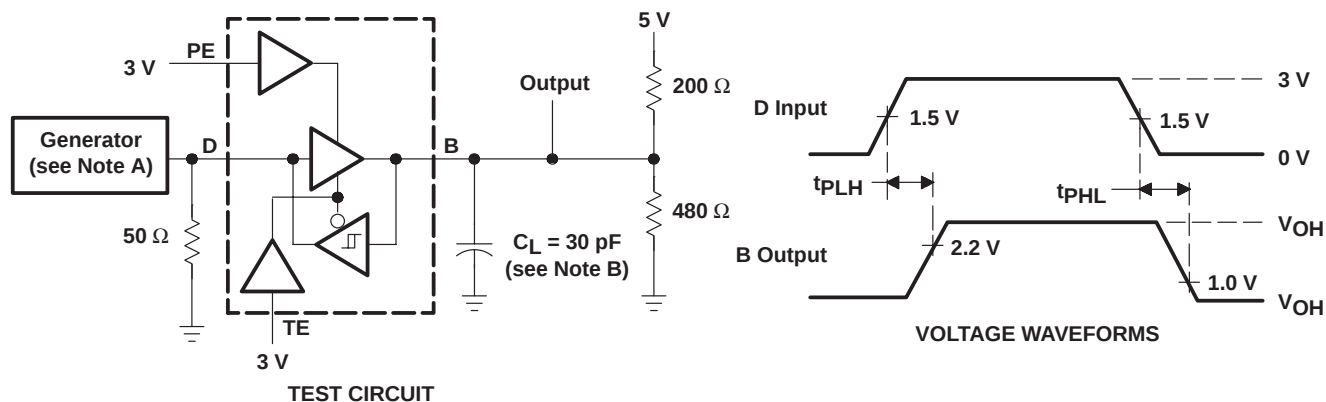
[†] All typical values are at $V_{CC} = 5$ V, $T_A = 25^{\circ}$ C.



switching characteristics, $V_{CC} = 5\text{ V}$, $C_L = 15\text{ pF}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

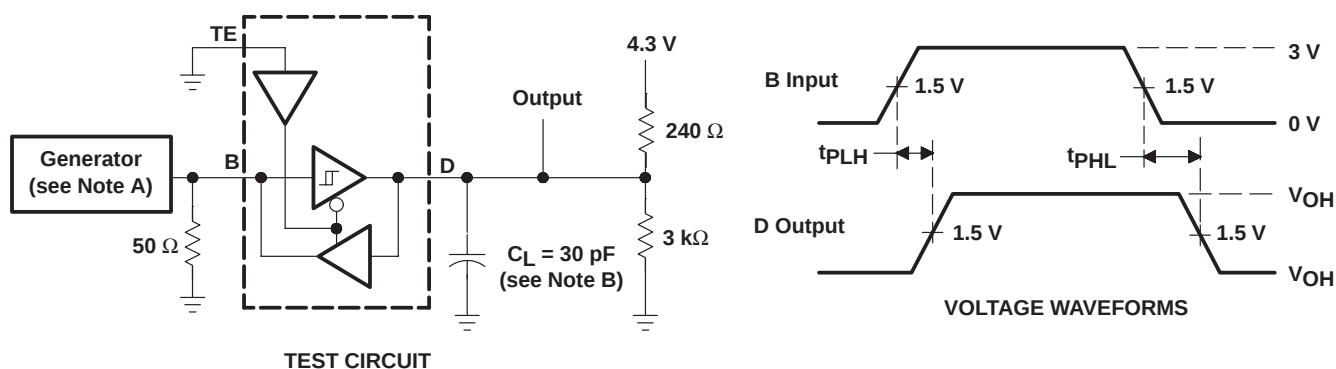
PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propation delay time, low- to high-level output	Terminal	Bus	$C_L = 30\text{ pF}$, See Figure 1		14	20	ns
t_{PHL}	Propagation delay time, high- to low-level output					14	20	
t_{PLH}	Propagation delay time, low- to high-level output	Bus	Terminal	$C_L = 30\text{ pF}$, See Figure 2		10	20	ns
t_{PHL}	Propagation delay time, high- to low-level output					15	22	
t_{PZH}	Output enable time to high level	TE	BUS	See Figure 3		25	35	ns
t_{PHZ}	Output disable time from high level					13	22	
t_{PZL}	Output enable time to low level					22	35	
t_{PLZ}	Output disable time from low level					22	32	
t_{PZH}	Output enable time to high level	TE	Terminal	See Figure 4		20	30	ns
t_{PHZ}	Output disable time from high level					12	20	
t_{PZL}	Output enable time to low level					23	32	
t_{PLZ}	Output disable time from low level					19	30	
t_{en}	Output pullup enable time	PE	Bus	See Figure 5		15	22	ns
t_{dis}	Output pullup disable time					13	20	

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: $PRR \leq 1 \text{ MHz}$, 50% duty cycle, $t_r \leq 6 \text{ ns}$, $t_f \leq \text{ns}$, $Z_O = 50 \Omega$.
 B. C_L includes probe and jig capacitance.

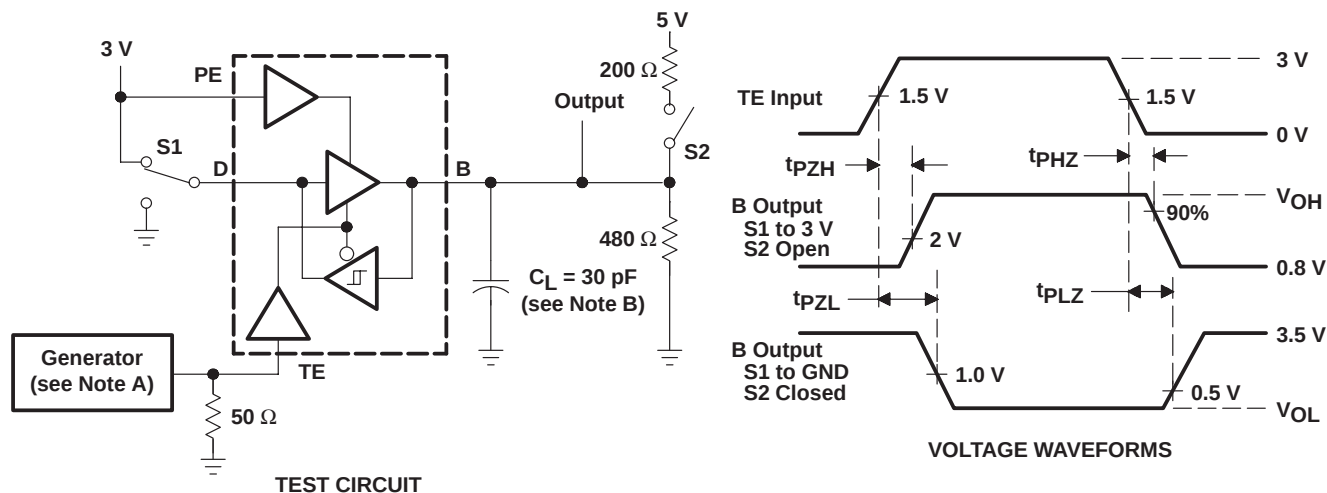
Figure 1. Terminal-to-Bus Test Circuit and Voltage Waveforms



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: $PRR \leq 1 \text{ MHz}$, 50% duty cycle, $t_r \leq 6 \text{ ns}$, $t_f \leq \text{ns}$, $Z_O = 50 \Omega$.
 B. C_L includes probe and jig capacitance.

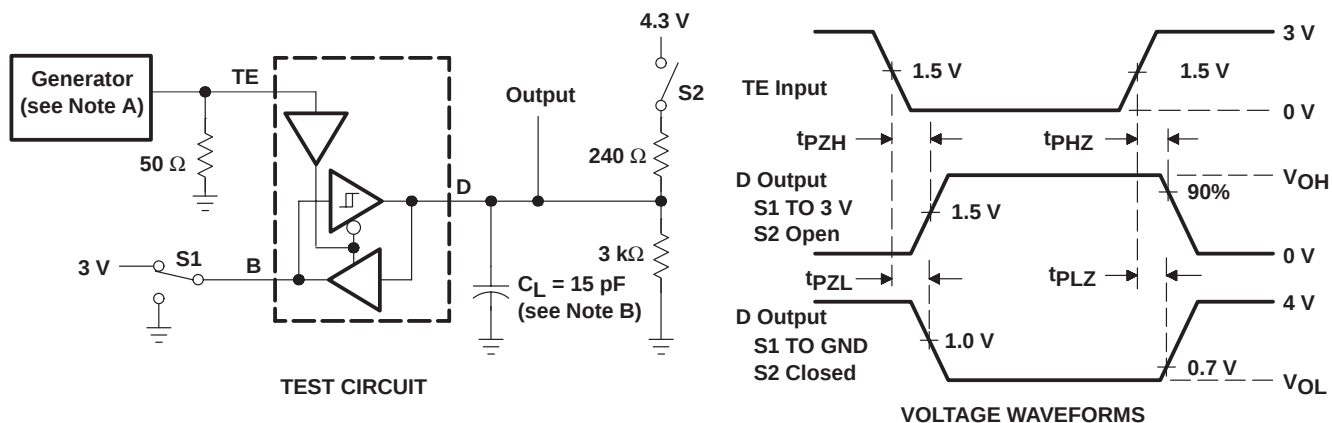
Figure 2. Bus-to-Terminal Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: $PRR \leq 1 \text{ MHz}$, 50% duty cycle, $t_r \leq 6 \text{ ns}$, $t_f \leq \text{ns}$, $Z_O = 50 \Omega$.
 B. C_L includes probe and jig capacitance.

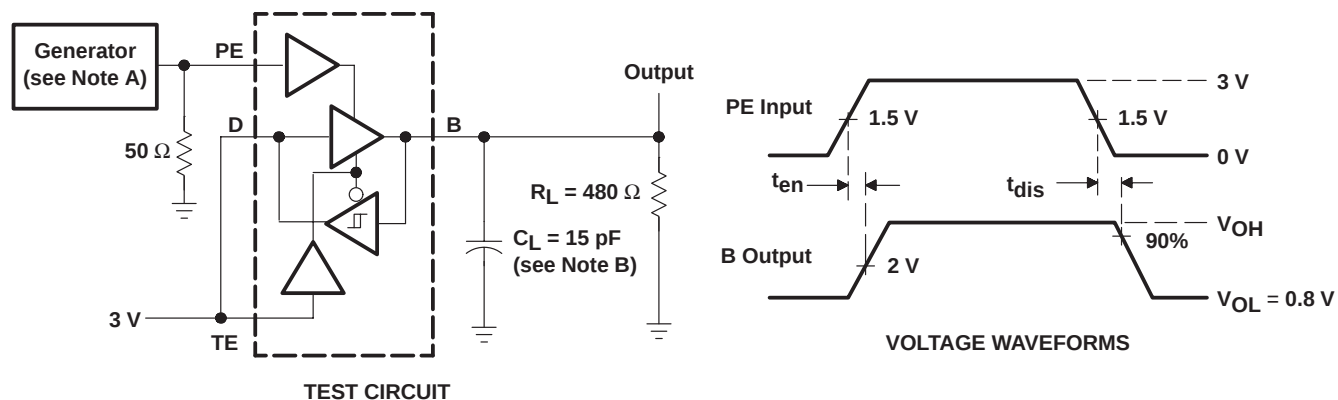
Figure 3. TE-to-Bus Test Circuit and Voltage Waveforms



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: $PRR \leq 1 \text{ MHz}$, 50% duty cycle, $t_r \leq 6 \text{ ns}$, $t_f \leq \text{ns}$, $Z_O = 50 \Omega$.
 B. C_L includes probe and jig capacitance.

Figure 4. TE-to-Terminal Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: $\text{PRR} \leq 1\ \text{MHz}$, 50% duty cycle, $t_r \leq 6\ \text{ns}$, $t_f \leq \text{ns}$, $Z_O = 50\ \Omega$.
- B. C_L includes probe and jig capacitance.

Figure 5. PE-to-Bus Pullup Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

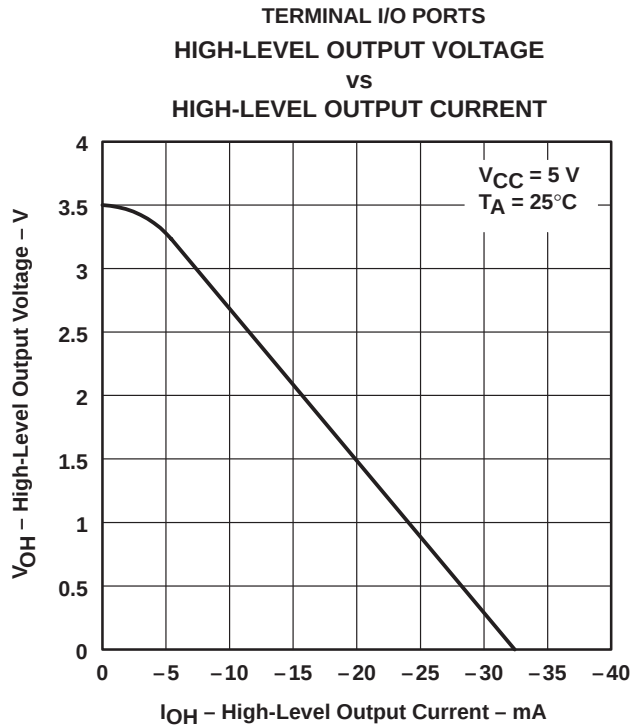


Figure 6

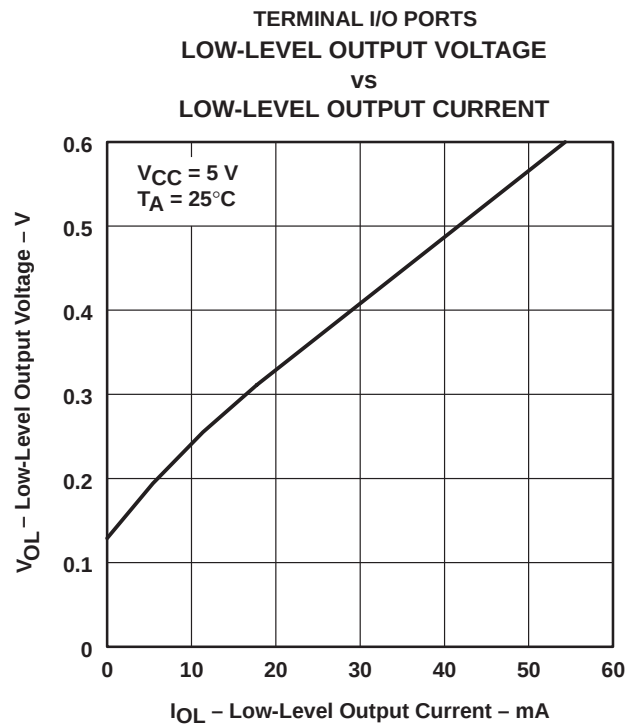


Figure 7

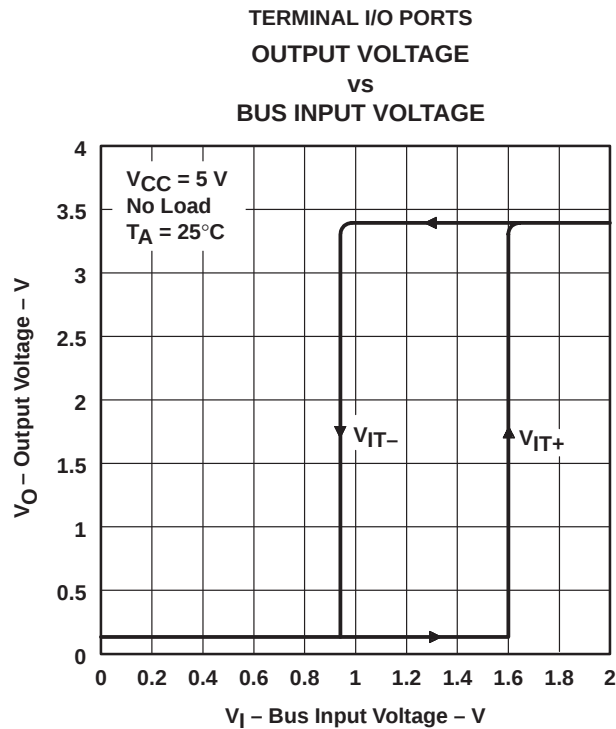


Figure 8

TYPICAL CHARACTERISTICS

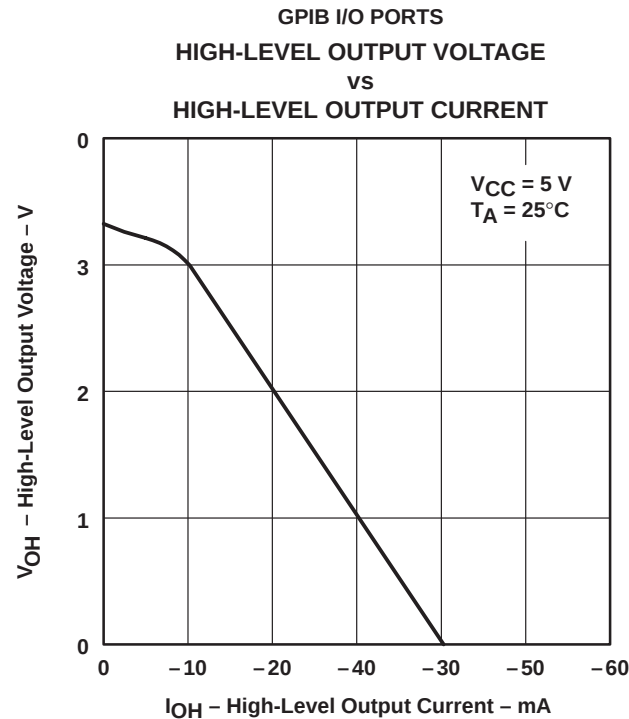


Figure 9

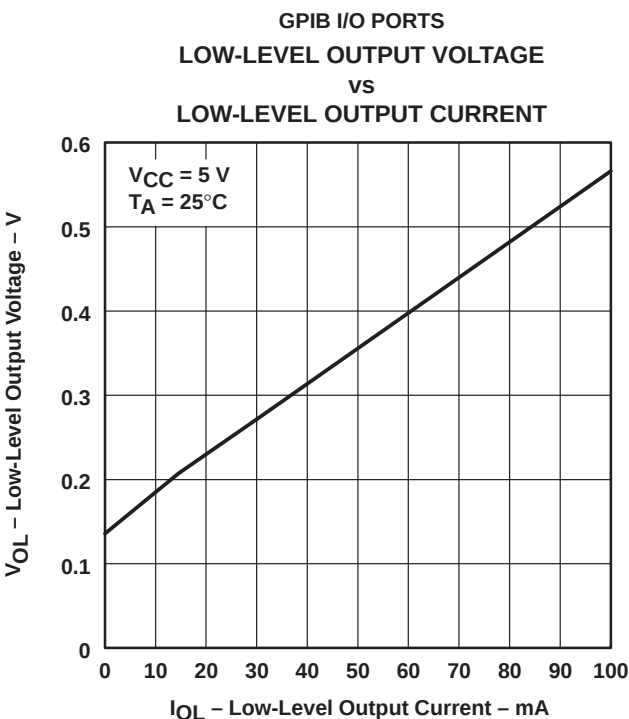


Figure 10

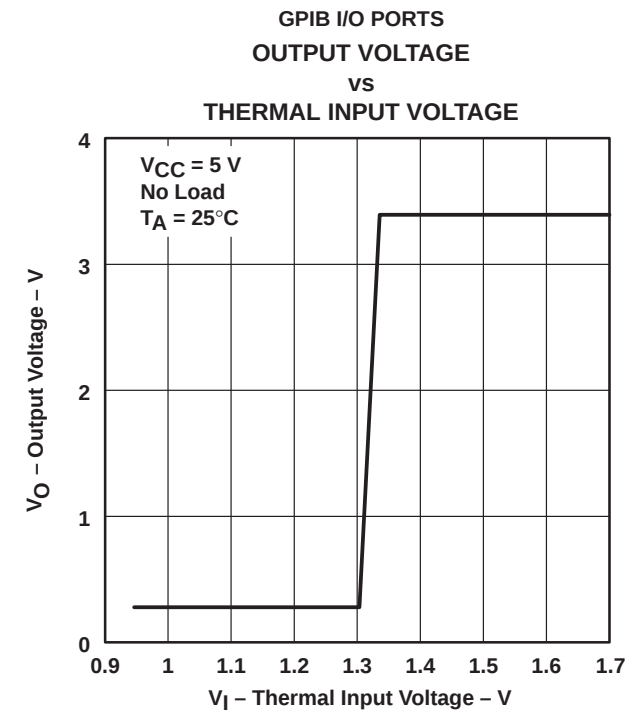


Figure 11

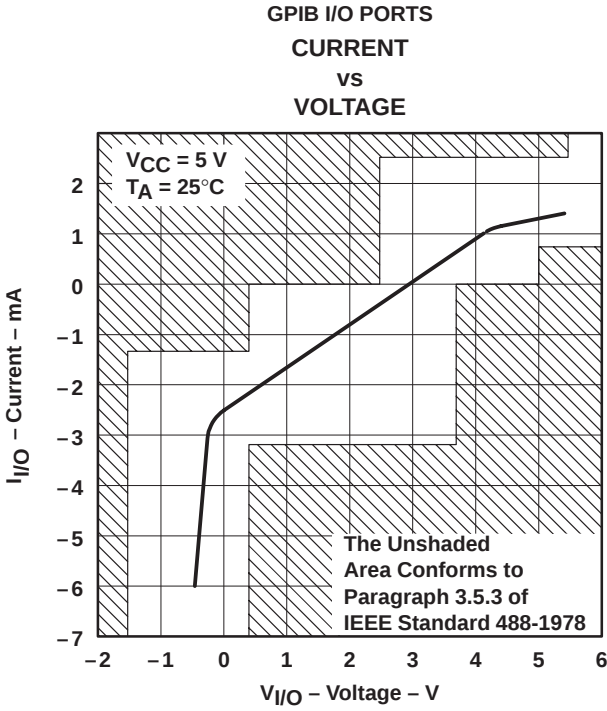


Figure 12

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75160BDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75160BDWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75160BDWVG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75160BDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75160BDWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75160BDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75160BN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75160BNE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75160BDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN75160BDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75160BDWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN75160BDWR	SOIC	DW	20	2000	367.0	367.0	45.0

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

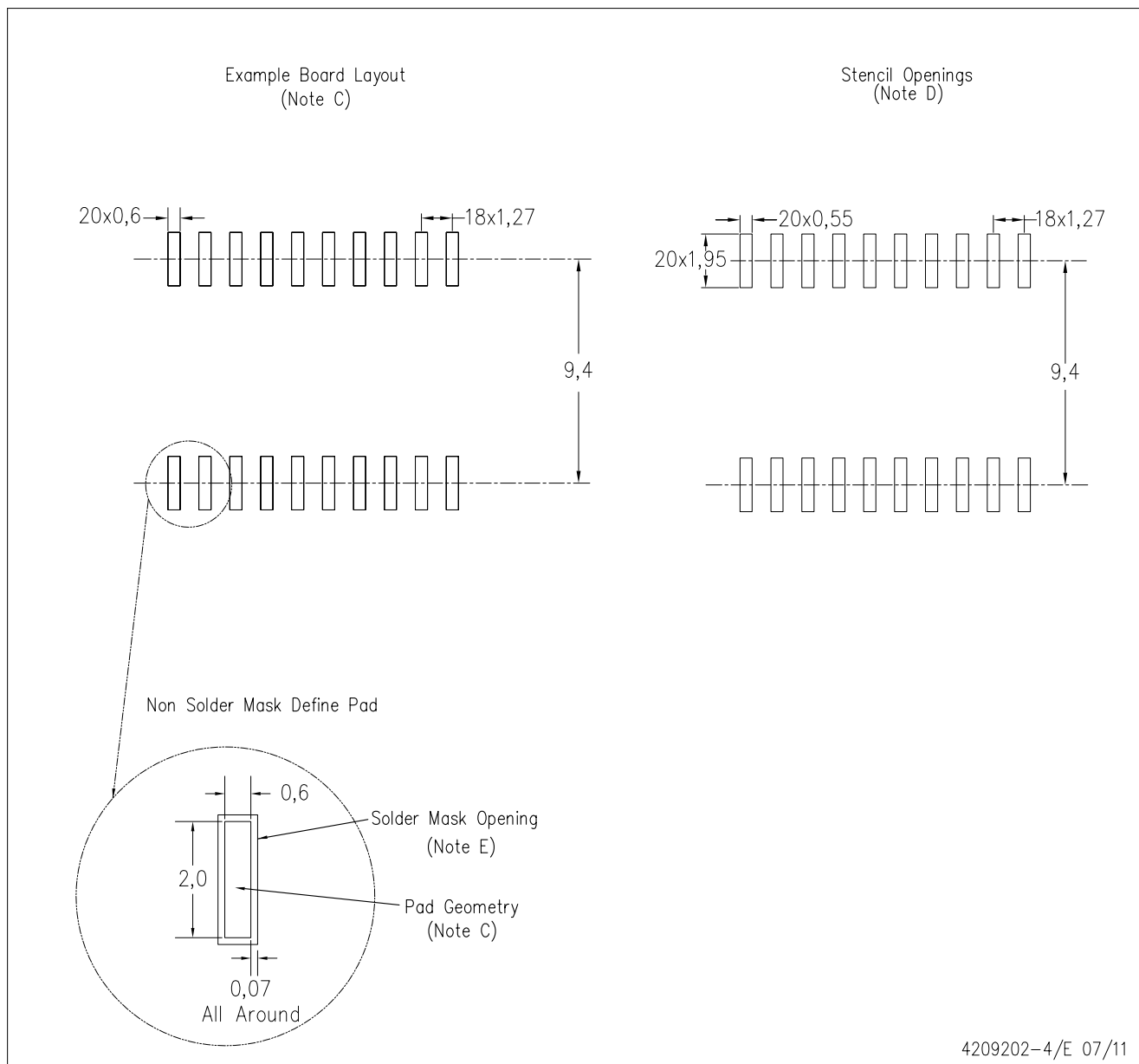
PLASTIC SMALL OUTLINE



- NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com